Filename: Pro97F0.tmp Generated: 4/26/2013 2:06:27 PM Arria V Ref Design

PMP8610

Quantity	Designator	Value	Description	PackageReference	PartNumber	Manufacturer
1	U1	TPS84320RUQ	IC, 4.5-V to 14.5-V Input, 3-A	QFN	TPS84320RUQ	п
1	U1	TPS51200DRC	Synchronous Buck IC, Sink/Source DDR Termination Regulator	DRC	TPS51200DRC	π
1	U2	TPS84B20 / TPS84C20 /	IC, 4.5-V to 14.5-V Input, 30-A Synchronous Buck, Integrated	QFN	TPS84C20RLG	п
2		LMZ31530	Power Solution			
3	U2, U6, U8 U7	TPS84A20RVQ TPS7A8300RGW	IC, IC, 2 A, LDO Voltage Regulator for High Speed Communication	QFN-20	TPS84A20RVQ TPS7A8300RGW	n n
	-		Systems			
1	TP2 TP1	5013 5010	TP-5013-ORANGE TP-5010-RED	0.125 x 0.125 inch 0.125 x 0.125 inch	5013 5010	Keystone Keystone
1	U3	TLC555D	IC, Timer, Low-Power CMOS	SO8	TLC555D	П
6	J1, J1, J2, J3, J3, J4		TBLK_15A_2X5.1MM	0.40 x 0.35 inch	ED120/2DS	OST
3	C43, C44, C47	10uF	Capacitor, Ceramic Chip, xxV, ±10%	805	STD	STD
2	U4, U5	SN74LVC1G14DCK	IC, Single Schmitt-Trigger Inverter	DCK-5	SN74LVC1G14DCK	Π
24	R1, R1, R2, R2, R3, R3, R4, R4, R5, R6, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, R17, R18, R19, R20	10K, 50, 100K, 0.453K, 10K, 324K, 10, 133k, 0.453K, 169K, 7320hms, 1K, 1K, 10K, 10K, 10K, 1K, 1K, 1K, 1.43K, 169K, 10K, 0.953K, 169K	R0603 1% R0603 1% R0603 1% <td>0603</td> <td>Std</td> <td>Std</td>	0603	Std	Std
1	C7	220 uF	R0603_1%, R0603_1% CAP_T520-7343	7343(D)	T530D337M006ATE006	Kemet
11	C1, C2, C9, C16, C17, C18, C19, C21, C28, C35, C42	68uF, 100uF, 220uF, 22uF, 22uF, 330uF, 330uF, 100uF, 220uF, 100uF, 220uF	CAP_POSCAP_D, Capacitor, Aluminum, SMT, WV, (temp), Itol), Capacitor, Aluminum, SMT, WV, (temp), Itol), Capacitor, Aluminum, SMT, WV, (temp), Itol), Capacitor, Aluminum, SMT, WV, (temp), Itol), CAP_POSCAP_D, CAP_POSCAP_D, CAP_POSCAP_D, CAP_POSCAP_D,	7343(D)	16TQC68M, 16TQC68M, 16TQC68M, STD, STD, STD, STD, STD, 16TQC68M, 16TQC68M, 16TQC68M, 16TQC68M	Sanyo, Sanyo, Sanyo, Panasonic, Panasonic, Panasonic, Panasonic, Sanyo, Sanyo, Sanyo, Sanyo
46	C2, C3, C3, C4, C4, C5, C5, C6, C6, C7, C8, C10, C11, C11, C12, C12, C13, C13, C14, C14, C15, C16, C17, C18, C19, C20, C21, C22, C22, C23, C33, C34, C24, C25, C26, C27, C30, C31, C32, C33, C36, C37, C38, C39, C40, C41	47uf, 22uF, 47uF, 22uF, 47uF, 22uF, 47uF, 100uF, 47uF, 100uF, 47uF, 1nF, 47uF, 10uF, 47uF, 1nF, 47uF, 10uF, 10uF, 10uF, 01uF, 10pF, 100uF, 22uF, 100uF, 100uF, 20uF, 100uF, 100uF, 100uF, 100uF, 100uF, 100uF, 100nF, 100uF, 100uF, 100nF, 22uF, 22uF, 22uF, 100uF, 100uF, 100uF, 100uF, 100uF, 100uF	C1210, CAP CER 47UF 16V 20% XSR 1210, C120, CAP CER 47UF 16V 20% XSR 1210, C1210, CAP CER 47UF 16V 20% XSR 1210, C1210, CAP CER 47UF 16V 20% XSR 1210, C1210, CAP CER 100UF 6.3V 20% XSR 1210, C1210, CAP CER 100UF 6.3V 20% XSR 1210, C1210, C1	1210	GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER61E226K, GRM32ER61E226K, GRM32ER61E226K, GRM32ER61E226K, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER61E226K, Std, GRM32ER61E226K, GRM32ER61E226K, GRM32ER61E226K, GRM32ER60.476M, GRM32ER61E226K, GRM32ER60.476M, GRM32ER61E226K, GRM32ER60.476M, GRM32ER61E226K, GRM32ER60.476M, GRM32ER61E226K, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER60.476M, GRM32ER61E226K, GRM32ER61	Murata, Murata, Murata, Murata, Murata, Murata, Murata, Murata, Murata, Murata, STD, Murata, STD, Murata, STD, Murata, STD, Murata, STD, Murata, Murata, STD, Murata
3	C8, C9, C15	47uF	Capacitor, Ceramic Chip, xxV, ±10%	1206	STD	Panasonic, STD, Nichico
1	C35	1uF	Capacitor, Ceramic Chip, xxV, ±10%	0805	STD	STD
1	C25	1uF	Capacitor, Ceramic Chip, 6.3V, ±10%	0603	STD	STD
·	1				1	
2	D1, D2	0.65V	Diode, Schottky, 30V, 0.2A, SOT-23	SOT-23	BAT54-7-F	Diodes Inc.
	D1, D2 C10, C29, C46 C1, C20, C34	0.65V {Value} 0.1uF	Diode, Schottky, 30V, 0.2A, SOT-23 C0805 C0805	SOT-23 805 805	BAT54-7-F STD STD	Diodes Inc. STD STD

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